

What is claimed is:

1. A conductive pattern forming composition, containing in a dispersion medium conductive fine particles composed of at least one kind of metal and a dispersant for dispersing the conductive fine particles, wherein the dispersant is a polymer containing a tertiary amine-type monomer in a main chain and a polyether-type nonionic monomer in a side chain.
2. The composition of claim 1, for forming a conductive pattern on a surface of a substrate by an ink jet system.
3. The composition of claim 1, wherein the conductive fine particles comprise copper.
4. The composition of claim 1, wherein the conductive fine particles have an average particle size of not less than 0.1 nm and not more than 20 nm.
5. The composition of claim 1, wherein the dispersion medium is an organic dispersion medium mainly composed of a water-insoluble organic solvent.
6. A method for forming a conductive pattern comprising:

drawing a droplet pattern on a surface of a substrate by droplets of the composition of claim 1, and heating the droplet pattern drawn in the drawing to impart conductivity to the droplet pattern.

7. The method of claim 6, wherein in the drawing, the droplet pattern is drawn by ejecting droplets of the conductive pattern forming composition by an ink jet system.

8. The method of claim 7, wherein in the drawing, the droplets of the conductive pattern forming composition are ejected from a nozzle having a nozzle size of 0.1 μm to 10 μm .

9. The method of claim 6, wherein in the drawing, a droplet pattern having a line width of 20 μm or less is drawn.

10. A method for producing a conductive pattern forming composition, comprising reducing a metal compound having at least one kind of metal in an aqueous dispersion medium containing a dispersant to obtain conductive fine particles, wherein a polymer containing a tertiary amine-type monomer in a main chain and a polyether-type nonionic monomer in a side chain is used as the dispersant.

11. The method of claim 10, wherein in the reducing, an organic amine compound is used as a reducing agent.

12. The method of claim 10, wherein in the reducing, a temperature of the aqueous dispersion medium is adjusted to 20°C to 60°C.

13. The method of claim 10, further comprising: interphase transferring the conductive fine particles and the dispersant from an aqueous dispersion medium phase to an organic dispersion medium phase which is mainly composed of a water-insoluble organic solvent, after the reducing.

14. The method of claim 13, further comprising purifying to remove at least a part of water soluble components in the organic dispersion medium phase by use of purified water, after the interphase transferring.

15. A method for producing a conductive pattern forming composition, comprising interphase transferring a dispersant and conductive fine particles composed of at least one kind of metal from an aqueous dispersion medium phase containing the dispersant and having dispersed therein the conductive fine particles to an organic dispersion medium phase mainly composed of a water-insoluble organic solvent, wherein a polymer containing a

tertiary amine-type monomer in a main chain and a polyether-type nonionic monomer in a side chain is used as the dispersant.

16. The method of claim 15, wherein in the interphase transferring, a temperature of the aqueous dispersion medium phase and the organic dispersion medium phase is adjusted to 50°C to 90°C.

17. The method of claim 15, wherein in the interphase transferring, a pH of the aqueous dispersion medium is adjusted to 7 to 10.

18. The method of claim 15, further comprising purifying to remove at least a part of water soluble components in the organic dispersion medium phase by use of purified water, after the interphase transferring.